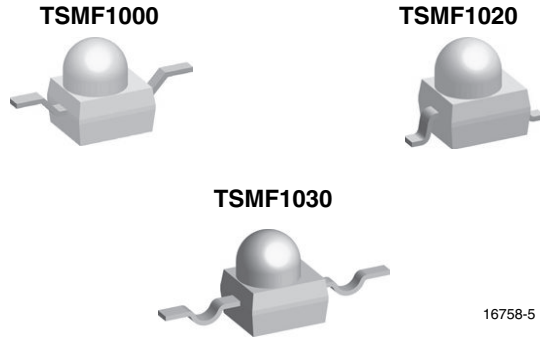




## High Speed Infrared Emitting Diode, RoHS-Compliant, 890 nm, Surface Emitter Technology



### FEATURES

- Package type: surface-mount
- Package form: GW, RGW, yoke
- Dimensions (L x W x H in mm): 2.5 x 2 x 2.7
- Peak wavelength:  $\lambda_p = 890 \text{ nm}$
- High radiant power
- Angle of half intensity:  $\phi = \pm 11^\circ$
- Low forward voltage
- Suitable for high pulse current operation
- Package matches with detector TEMD1000
- Floor life: 168 h, MSL 3, according to J-STD-020
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



RoHS COMPLIANT

### DESCRIPTION

TSMF1000 series are infrared, 890 nm emitting diodes based on surface emitter chip technology with high radiant power and high speed, molded in clear, untinted plastic packages (with lens) for surface mounting (SMD).

### APPLICATIONS

- IrDA compatible data transmission
- Miniature light barrier
- Photointerrupters
- Optical switch
- Control and drive circuits
- Shaft encoders

PRODUCT SUMMARY				
COMPONENT	$I_e$ (mW/sr)	$\phi$ (°)	$\lambda_p$ (nm)	$t_r$ (ns)
TSMF1000	27	$\pm 11$	890	15
TSMF1020	27	$\pm 11$	890	15
TSMF1030	27	$\pm 11$	890	15

#### Note

- Test conditions see table "Basic Characteristics"

ORDERING INFORMATION			
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM
TSMF1000	Tape and reel	MOQ: 1000 pcs, 1000 pcs/reel	Reverse gullwing
TSMF1020	Tape and reel	MOQ: 1000 pcs, 1000 pcs/reel	Gullwing
TSMF1030	Tape and reel	MOQ: 1000 pcs, 1000 pcs/reel	Yoke

#### Note

- MOQ: minimum order quantity



ABSOLUTE MAXIMUM RATINGS ( $T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified)				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		$V_R$	5	V
Forward current		$I_F$	100	mA
Peak forward current	$t_p/T = 0.5, t_p = 100\text{ }\mu\text{s}$	$I_{FM}$	200	mA
Surge forward current	$t_p = 100\text{ }\mu\text{s}$	$I_{FSM}$	1	A
Power dissipation		$P_V$	190	mW
Junction temperature		$T_j$	100	$^{\circ}\text{C}$
Ambient temperature range		$T_{amb}$	-40 to +85	$^{\circ}\text{C}$
Storage temperature range		$T_{stg}$	-40 to +100	$^{\circ}\text{C}$
Soldering temperature	$t \leq 5\text{ s}$	$T_{sd}$	260	$^{\circ}\text{C}$
Thermal resistance junction to ambient	JESD51	$R_{thJA}$	250	K/W

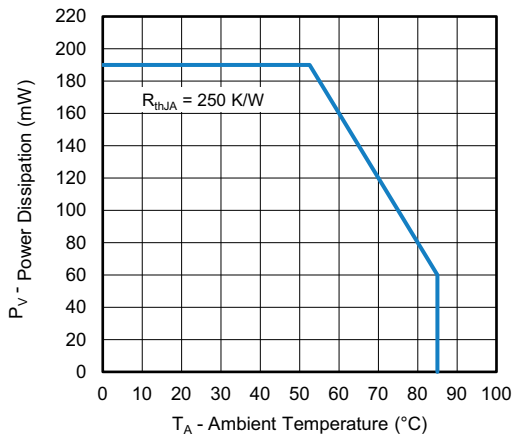


Fig. 1 - Power Dissipation vs. Ambient Temperature

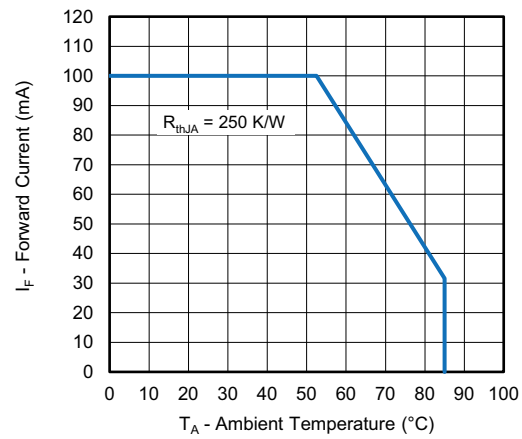


Fig. 2 - Forward Current vs. Ambient Temperature

BASIC CHARACTERISTICS ( $T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	$I_F = 20\text{ mA}$	$V_F$	-	1.3	1.5	V
	$I_F = 100\text{ mA}, t_p = 100\text{ }\mu\text{s}$	$V_F$	-	1.5	-	V
	$I_F = 1\text{ A}, t_p = 100\text{ }\mu\text{s}$	$V_F$	-	2.6	-	V
Temperature coefficient of $V_F$	$I_F = 20\text{ mA}$	$TK_{V_F}$	-	-1.4	-	mV/K
Reverse current		$I_R$	Not designed for reverse operation			$\mu\text{A}$
Junction capacitance	$V_R = 0\text{ V}, f = 1\text{ MHz}, E = 0$	$C_j$	-	56	-	pF
Radiant intensity	$I_F = 20\text{ mA}$	$I_e$	15	27	40	mW/sr
	$I_F = 100\text{ mA}, t_p = 100\text{ }\mu\text{s}$	$I_e$	-	155	-	mW/sr
Radiant power	$I_F = 20\text{ mA}, t_p = 20\text{ ms}$	$\phi_e$	-	10	-	mW
Temperature coefficient of $\phi_e$	$I_F = 20\text{ mA}$	$TK_{\phi_e}$	-	-0.3	-	%/K
Angle of half intensity		$\phi$	-	$\pm 11$	-	$^{\circ}$
Peak wavelength	$I_F = 20\text{ mA}$	$\lambda_p$	-	890	-	nm
Spectral bandwidth	$I_F = 20\text{ mA}$	$\Delta\lambda$	-	35	-	nm
Temperature coefficient of $\lambda_p$	$I_F = 20\text{ mA}$	$TK_{\lambda_p}$	-	0.3	-	nm/K
Rise time	$I_F = 20\text{ mA}$	$t_r$	-	15	-	ns
Fall time	$I_F = 20\text{ mA}$	$t_f$	-	15	-	ns

## BASIC CHARACTERISTICS (T<sub>amb</sub> = 25 °C, unless otherwise specified)

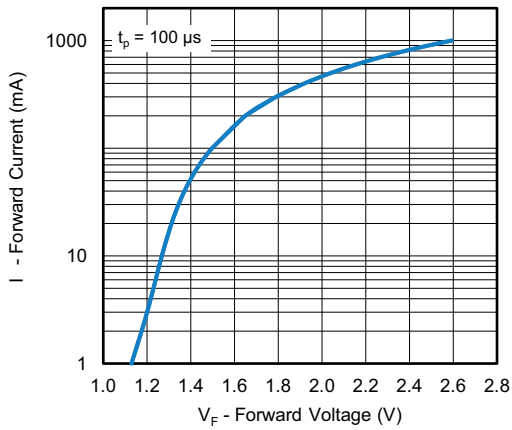


Fig. 3 - Forward Current vs. Forward Voltage

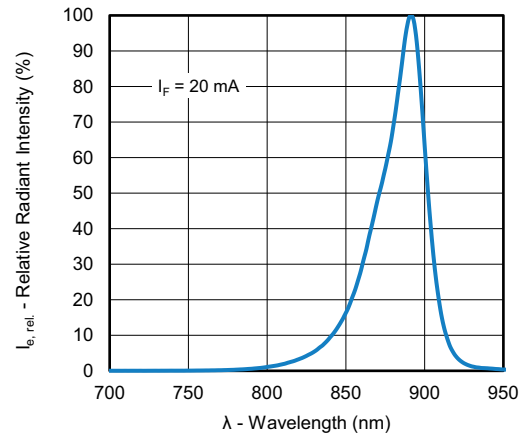


Fig. 6 - Relative Radiant Intensity vs. Wavelength

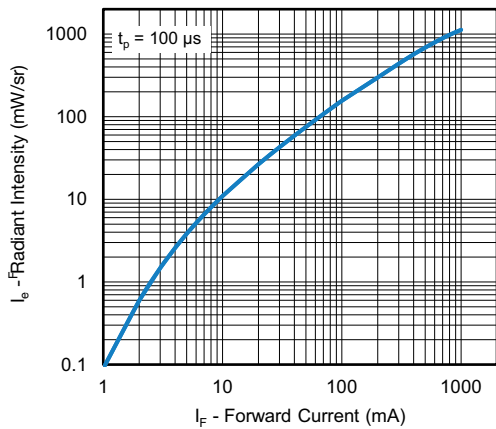


Fig. 4 - Radiant Intensity vs. Forward Current

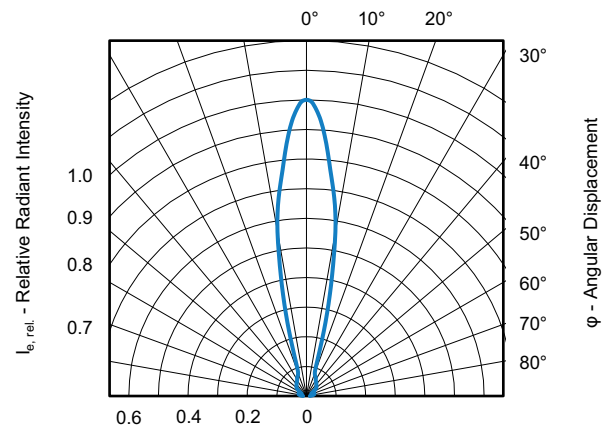


Fig. 7 - Relative Radiant Intensity vs. Angular Displacement

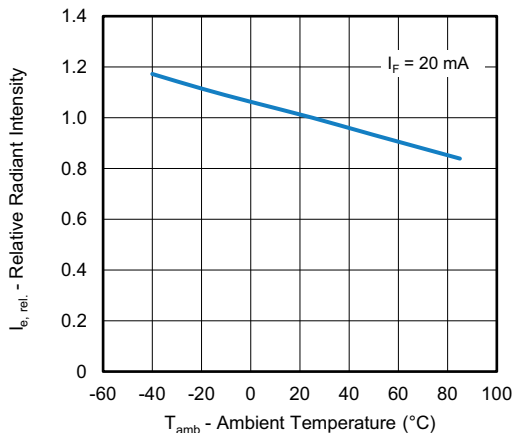


Fig. 5 - Relative Radiant Intensity vs. Ambient Temperature

**PRECAUTIONS FOR USE**

**1. Over-Current-Proof**

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (burn out will happen).

**2. Storage**

- Storage temperature and rel. humidity conditions are: 5 °C to 35 °C, R.H. 60 %.
- Floor life must not exceed 168 h, according to JEDEC® level 3, J-STD-020.  
Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp proof box with desiccant.  
Considering tape life, we suggest to use products within one year from production date.
- If opened more than one week in an atmosphere 5 °C to 35 °C, R.H. 60 %, devices should be treated at 60 °C ± 5 °C for 15 h.
- If humidity indicator in the package shows pink color (normal blue), then devices should be treated with the same conditions as 2.3.

**REFLOW SOLDER PROFILE**

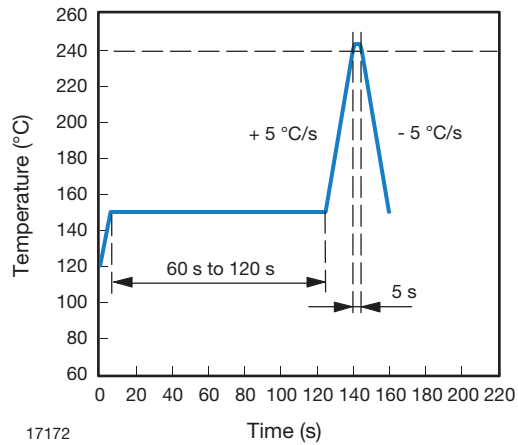


Fig. 8 - Lead Tin (SnPb) Reflow Solder Profile

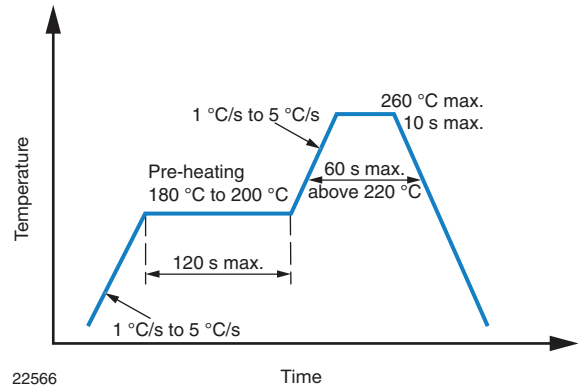
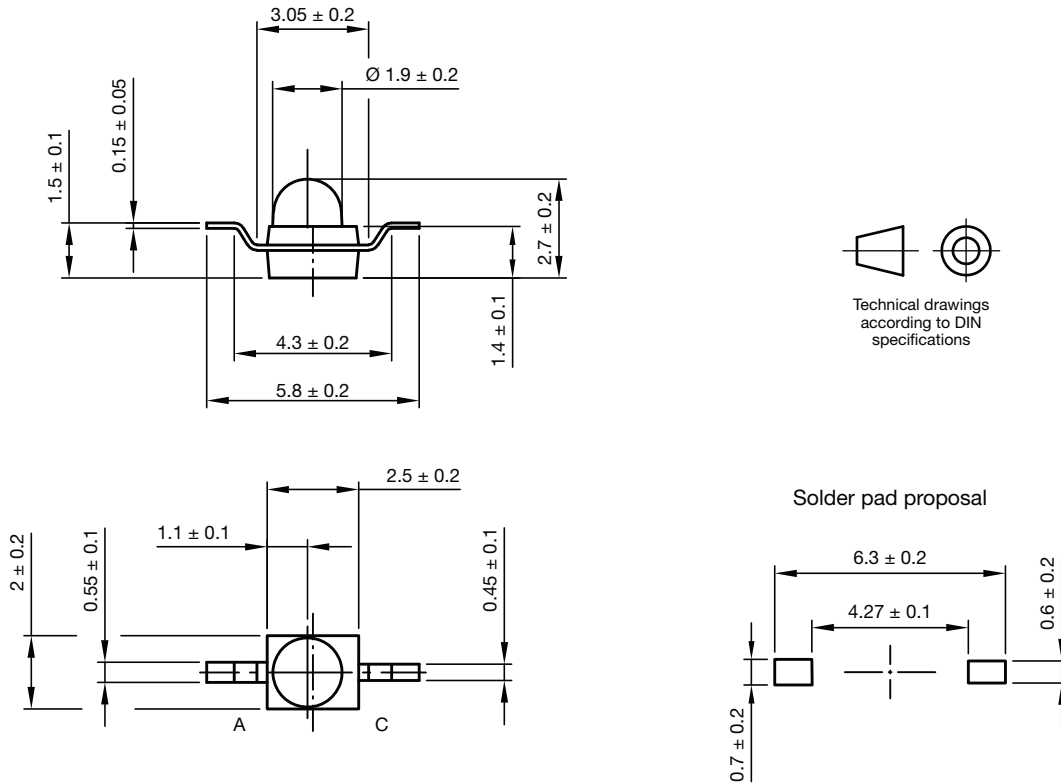


Fig. 9 - Lead (Pb)-Free Reflow Solder Profile According to J-STD-020

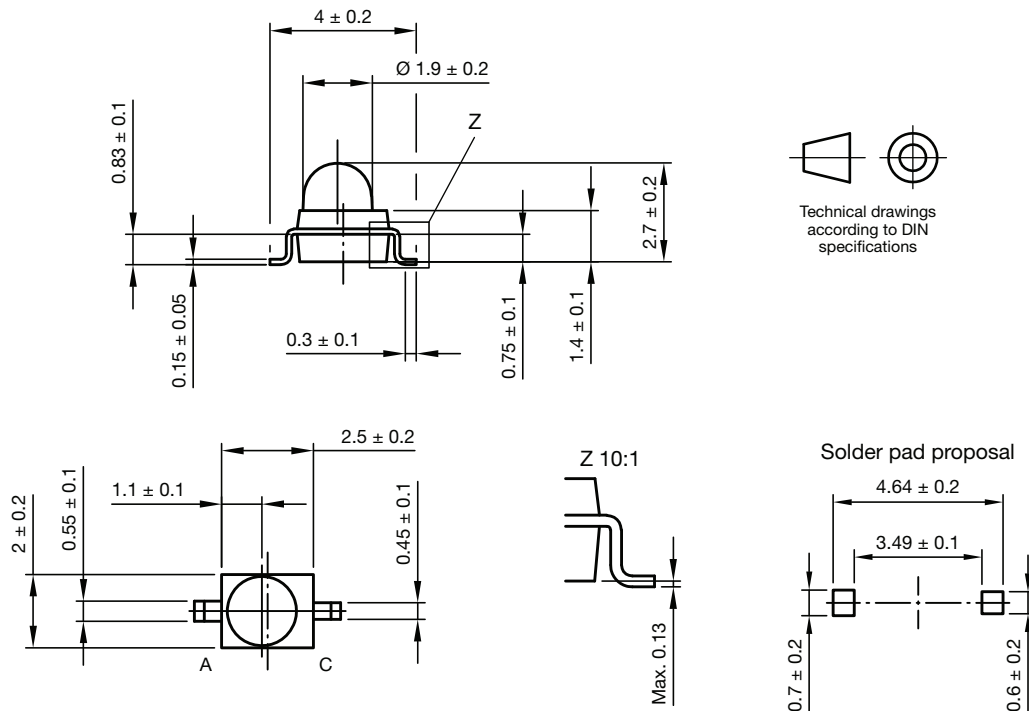


## PACKAGE DIMENSIONS in millimeters: TSMF1000



Drawing-No.: 6.544-5326.03-4  
Issue: 1; 15.09.2021

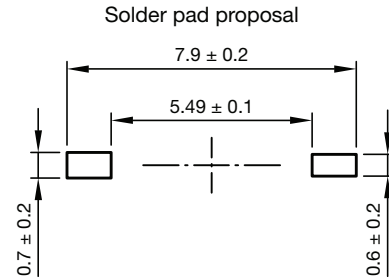
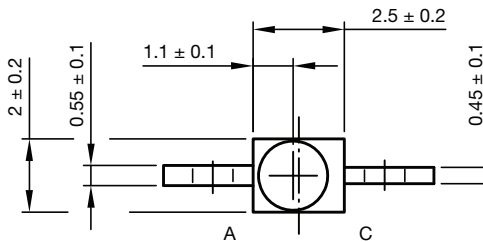
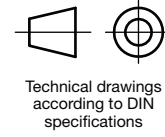
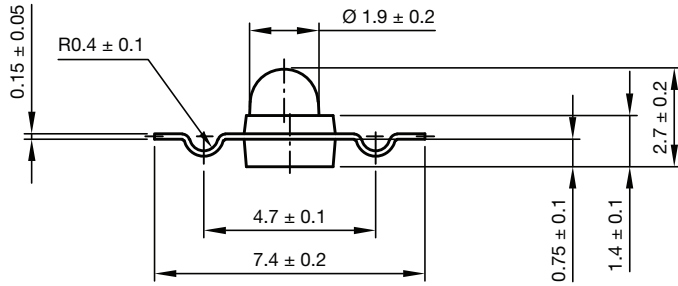
## PACKAGE DIMENSIONS in millimeters: TSMF1020



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Issue: 1; 15.09.2021

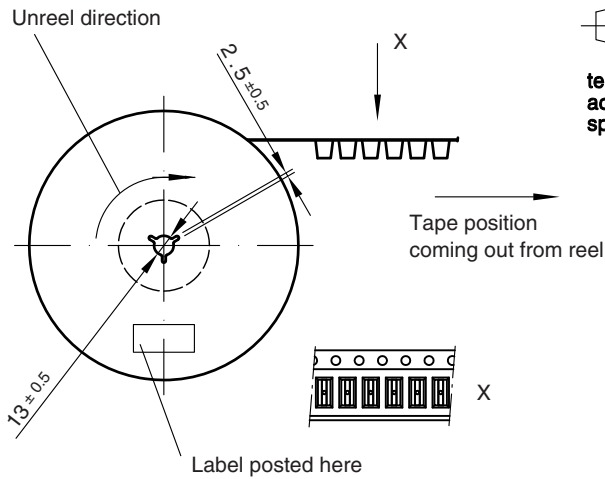
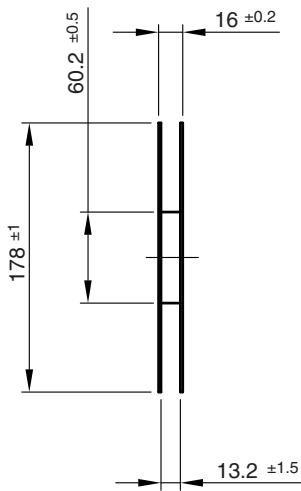


## PACKAGE DIMENSIONS in millimeters: TSMF1030

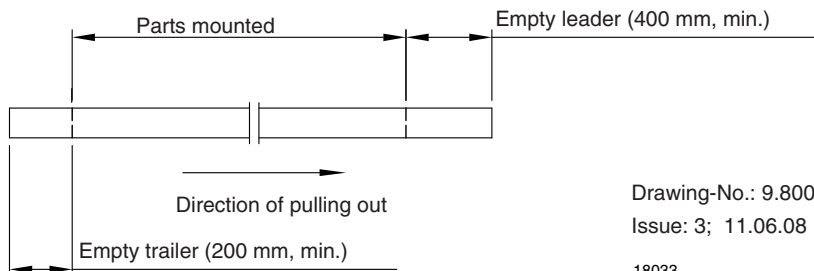


Drawing-No.: 6.544-5329.03-4  
Issue: 1; 15.09.2021

## REEL DIMENSIONS in millimeters



### Leader and trailer tape:



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Issue: 3; 11.06.08

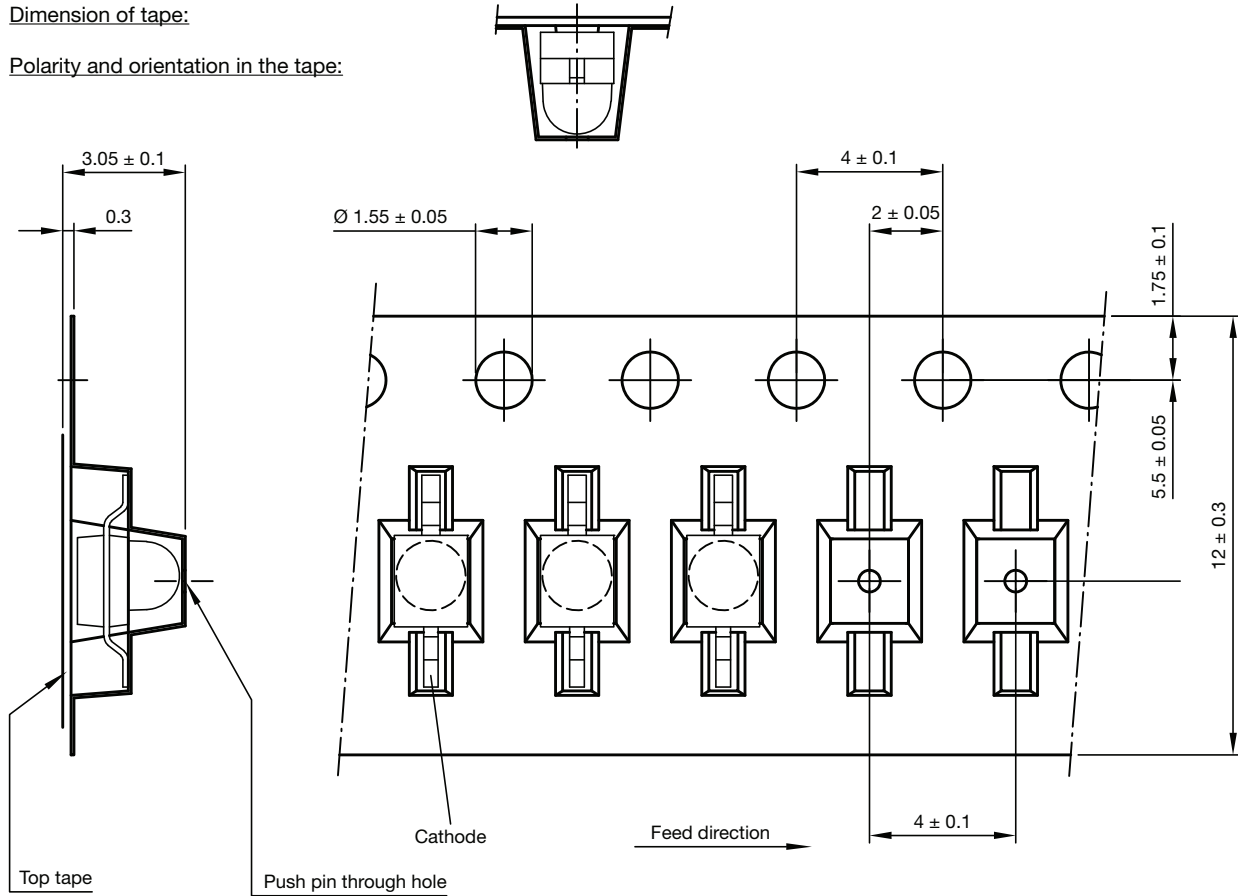
18033



## TAPING DIMENSIONS in millimeters: TSMF1000

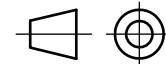
Dimension of tape:

Polarity and orientation in the tape:



Quantity per reel: 1000 pieces

Drawing-No.: 9.700-5268.02-4  
Issue: 1; 28.09.2021

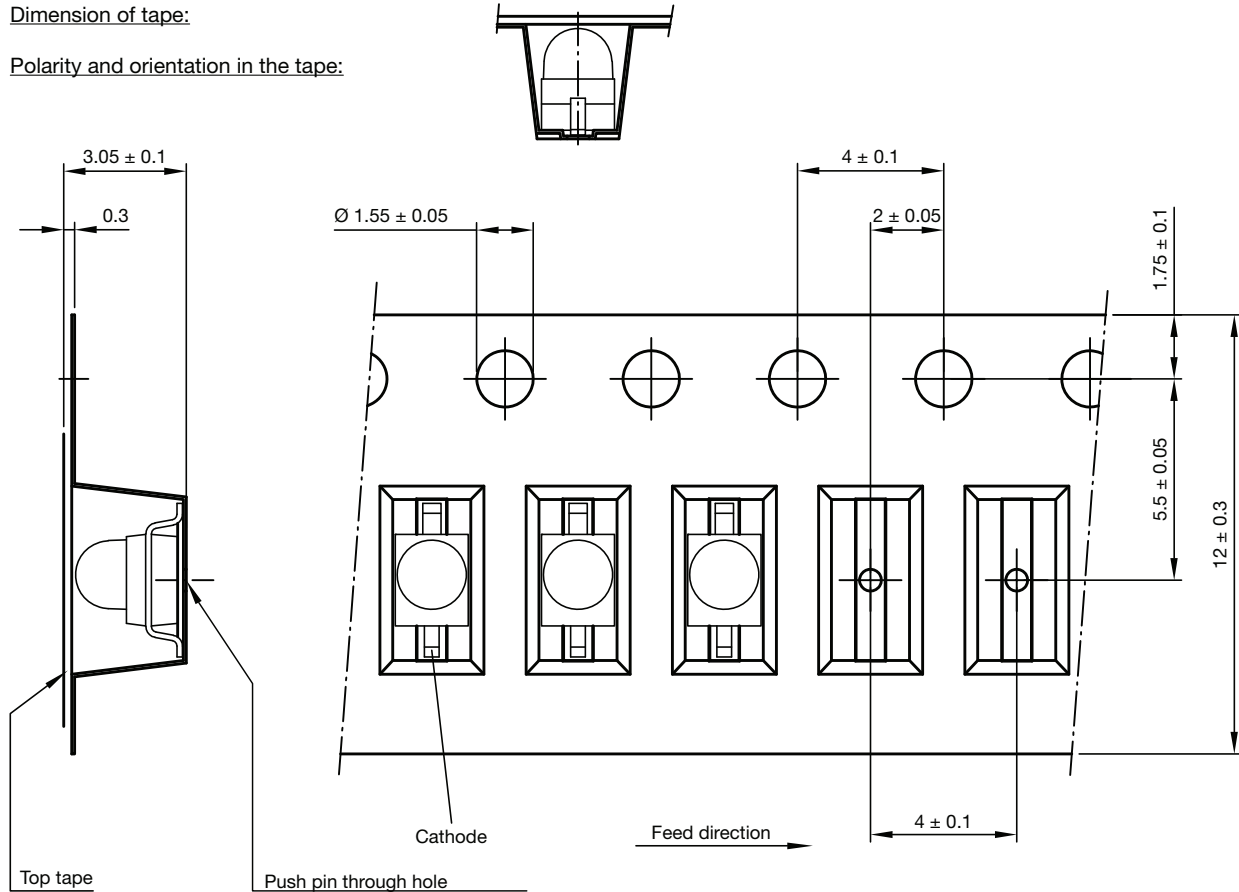


Technical drawings according to DIN specifications

## TAPING DIMENSIONS in millimeters: TSMF1020

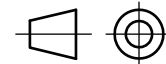
Dimension of tape:

Polarity and orientation in the tape:



Quantity per reel: 1000 pieces

Drawing-No.: 9.700-5269.02-4  
Issue: 1; 28.09.2021



Technical drawings according to DIN specifications

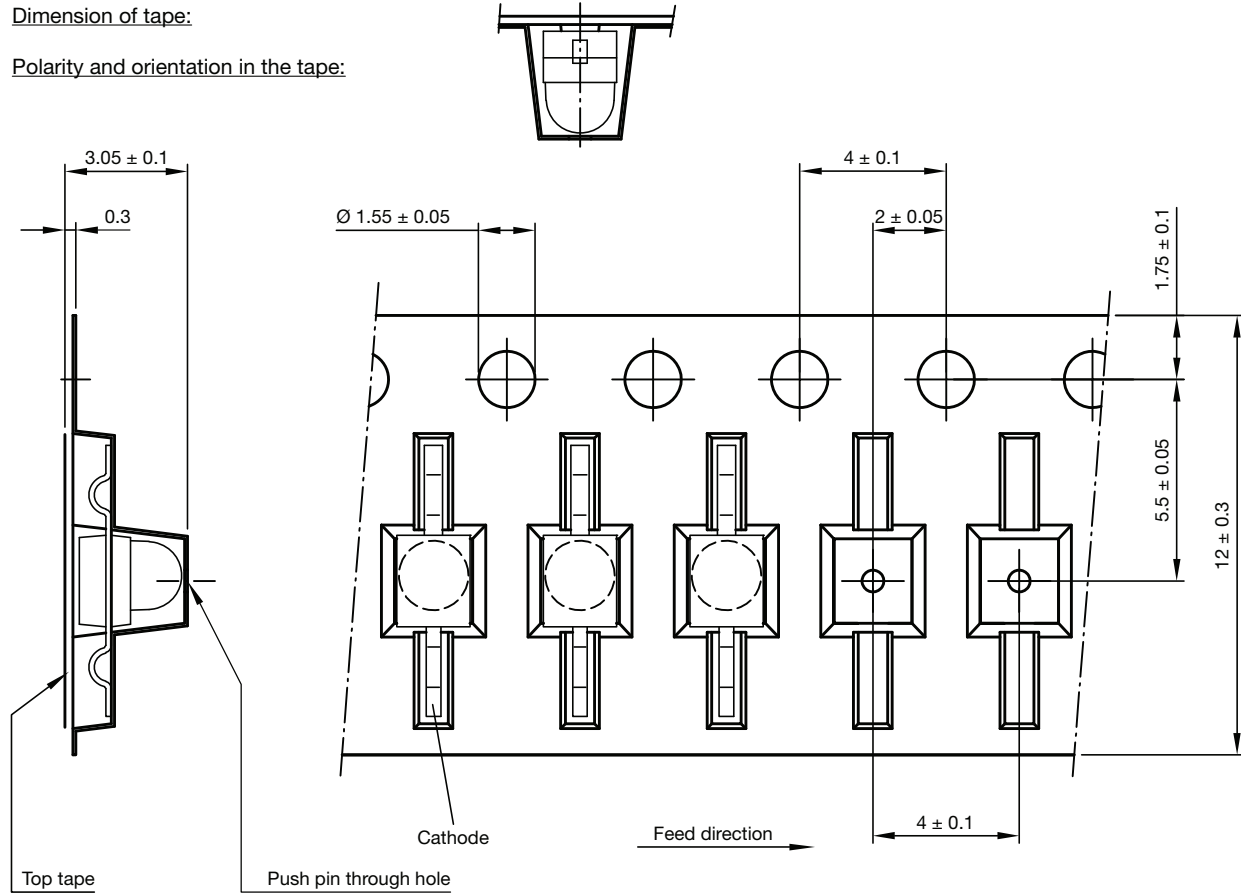




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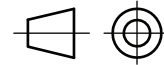
Dimension of tape:

Polarity and orientation in the tape:



Quantity per reel: 1000 pieces

Drawing-No.: 9.700-5270.02-4  
Issue: 1; 28.09.2021



Technical drawings according to DIN specifications



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